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PATENT OFFICE
NOTICE OF GROUND OF REJECTION

Applicant : Sharp Kabushiki Kaisha
Attorney : Kim & Chang
Pat. Appln. No. : 10-1996-0061666
Title of the Invention : Thickness Measurement Apparatus of Thin
Film Using Light Interference Method

It is noticed that the present application is rejected under the provision of Article 63 of the Patent Law on the following grounds. If the applicant has any argument or amendment to be filed, the applicant may file a Written Opinion or Amendment by the date indicated above. (The due date can be extended, one month for each time, and any notification acknowledging an extension of a due date is not issued.)

GROUND S

The inventions as recited in claims 1, 3, 4, 9, 11, 12, 31-40 of the subject application would have been readily made by those skilled in the art before the subject application was filed, as set forth below. Therefore the claims are not allowable under Korean Patent Law § 29(2).

REMARKS

Claims 1, 3, 4, 9, 11, 12, 31-40 of the present invention are characterized in including, as the main structural component, a light receiving unit directing light perpendicularly and receiving reflected light, an analyze unit analyzing the thickness of a thin film according to the intensity of the reflected light, a branch type optical fiber, a spectroscope dividing reflected light, a film thickness calculation unit and the like in a thin film thickness measurement apparatus and method using the light

interference method. However, Japanese Patent Laying-Open No. 8-136710 (May 31, 1996) discloses art related to a thin film fabrication method including a measurement apparatus that directs light perpendicular to a sample and receives light reflected therefrom to analyze the thickness of a thin film according to the intensity of the reflected light, a branch type optical fiber, and the like. Japanese Patent Laying-Open No. 11-184104 (July 9, 1997) discloses art related to a thin film thickness measurement apparatus using the light interference method, including a spectroscope dividing reflected light, and a film thickness calculation unit. It is therefore recognized that the invention of the present application could have been readily invented by a simple combination of the above two prior art.

Appended Documents:

Japanese Patent Laying Open No. 8-136710

Japanese Patent Laying Open No. 11-184104

June 4, 2002

Patent Office, Examination Division 4